

Description

The Si2308BDS-T1-GE3 uses advanced trench technology to provide excellent $R_{\text{DS(ON)}}$, low gate charge and operation with gate voltages as low as 2.5V. This device is suitable for use as a Battery protection or in other Switching application.

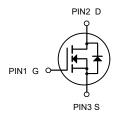
D G SOT-23-3L

General Features

 $V_{DS} = 60V, I_{D} = 4.5A$

 $R_{DS(ON)}$ < 75m Ω @ V_{GS} =10V

 $R_{DS(ON)} < 90 \text{m}\Omega$ @ V_{GS} =4.5V



N-Channel MOSFET

Application

Power management

High power and current handing capability
Lead free product is acquired
Surface mount package
PWM applications
Load switch

Package Marking and Ordering Information

Product ID	Pack	Brand	Qty(PCS)
Si2308BDS-T1-GE3	SOT-23-3L	HXY MOSFET	3000

Absolute Maximum Ratings (T_A=25 ℃ unless otherwise noted)

Symbol	Parameter	Limit	Unit
Vps	Drain-Source Voltage	60	V
Vgs	Gate-Source Voltage	±20	V
I _D	Drain Current-Continuous	4.5	А
Ідм	Drain Current-Pulsed (Note 1)	15	А
P _D	Maximum Power Dissipation	8	W
Тл,Тѕтс	Operating Junction and Storage Temperature Range	-55 To 150	$^{\circ}$
Reja	Thermal Resistance,Junction-to-Ambient (Note 2)	89	°C/W

Electrical Characteristics (T_J=25 °C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V , I _D =250uA	60			V
D-avanii	Static Drain-Source On-Resistance ²	V _{GS} =10V , I _D =5A		70	75	mΩ
R _{DS(ON)}		V _{GS} =4.5V , I _D =5A		80	90	
V _{GS(th)}	Gate Threshold Voltage	V _{GS} =V _{DS} , I _D =250uA	1.2		2.5	V
1		V _{DS} =48V , V _{GS} =0V , T _J =25°C			1	uA
Ipss	Drain-Source Leakage Current	V _{DS} =48V , V _{GS} =0V , T _J =55°C			5	
I _{GSS}	Gate-Source Leakage Current	V _{GS} =±20V , V _{DS} =0V			±100	nA
gfs	Forward Transconductance	V _{DS} =5V , I _D =5A		7		S
Qg	Total Gate Charge (10V)			5.5		nC
Qgs	Gate-Source Charge	V _{DS} =12V , V _{GS} =10V , I _D =5A		1.8		
Q_{gd}	Gate-Drain Charge			2.4		
T _{d(on)}	Turn-On Delay Time			6		
Tr	Rise Time	V_{DD} =12V , V_{GS} =10V , R_{G} =3.3 Ω		10		ns
T _{d(off)}	Turn-Off Delay Time	I _D =5A		15		
Tf	Fall Time			7		
Ciss	Input Capacitance			695		
Coss	Output Capacitance	V _{DS} =15V , V _{GS} =0V , f=1MHz		148		pF
Crss	Reverse Transfer Capacitance			7		
Is	Continuous Source Current ^{1,5}	V =V =OV Farea Current			17	Α
Ism	Pulsed Source Current ^{2,5}	──V _G =V _D =0V , Force Current			50	Α
V _{SD}	Diode Forward Voltage ²	V _{GS} =0V , I _S =1A , T _J =25°C			1.2	V

Note:

- 1. The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width \leq 300us , duty cycle \leq 2%
- 3. The EAS data shows Max. rating . The test condition is V_{DD} =25V, V_{GS} =10V,L=0.1mH, I_{AS} =15A
- 4. The power dissipation is limited by 150°C junction temperature
- 5. The data is theoretically the same as I_D and I_{DM} , in real applications, should be limited by total power dissipation.

Typical Characteristics

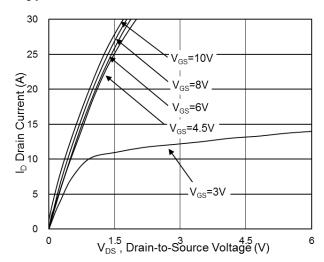


Fig.1 Typical Output Characteristics

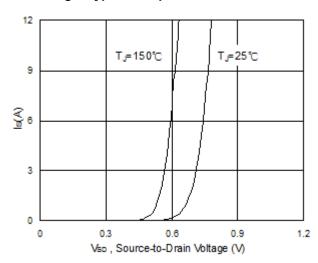


Fig.3 Forward Characteristics of Reverse

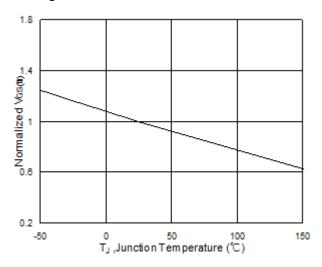


Fig.5 Normalized $V_{\text{GS(th)}}$ vs. T_{J}

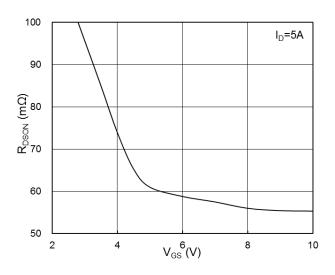


Fig.2 On-Resistance vs. Gate-Source Voltage

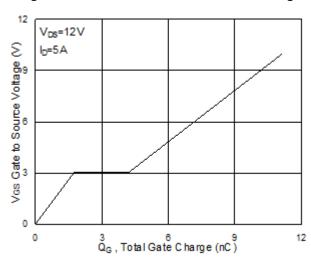


Fig.4 Gate-Charge Characteristics

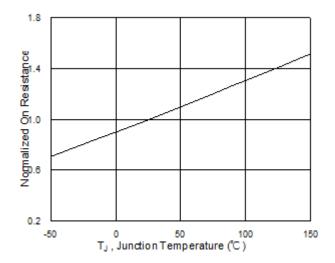
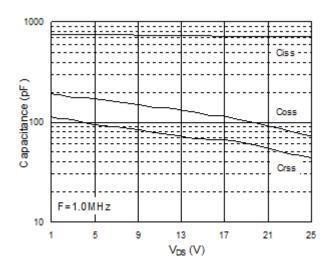


Fig.6 Normalized R_{DSON} vs. T_J



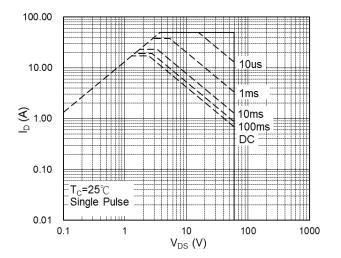


Fig.7 Capacitance

Fig.8 Safe Operating Area

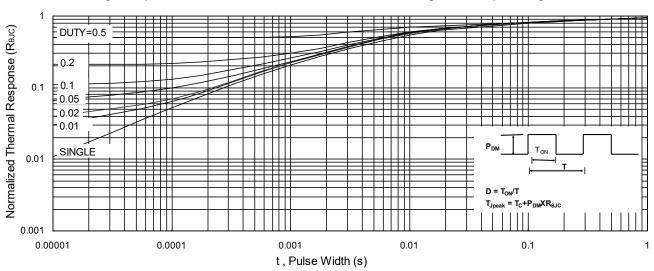


Fig.9 Normalized Maximum Transient Thermal Impedance

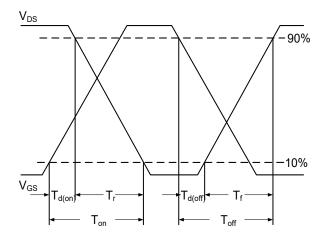


Fig.10 Switching Time Waveform

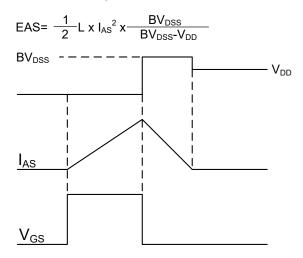
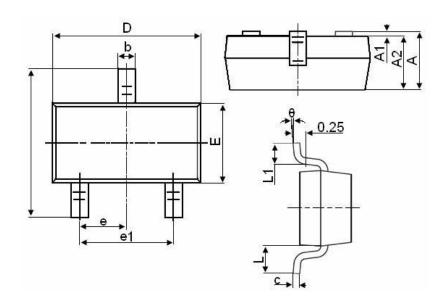


Fig.11 Unclamped Inductive Switching Waveform



SOT-23-3LPackage Information



Symbol	Dimensions in Millimeters		
	MIN.	MAX.	
А	1.050	1.250	
A1	0.000	0.100	
A2	1.050	1.150	
b	0.300	0.500	
С	0.100	0.200	
D	2.800	3.000	
E	1.500	1.700	
E1	2.650	2.950	
е		0.950TYP	
e1	1.800	2.000	
L	0.550REF		
L1	0.300	0.600	
θ	0°	8°	



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